

# LNPTM STAT-KONTM COMPOUND DX10315C

## DESCRIPTION

LNP STAT-KON DX10315C compound is based on Polycarbonate (PC) resin containing 15% carbon fiber. Added features of this grade include: LNP Clean Compounding Technology, Low LPC, Low Ionics, Low Outgassing, Low C18-C40 Hydrocarbons, Electrically Conductive.

GENERAL INFORMATION	
Features	Electrically Conductive, Low ionics/Outgassing/Liquid particle count, Carbon fiber filled, High stiffness/Strength, No PFAS intentionally added
Fillers	Carbon Fiber, Carbon Powder
Polymer Types	Polycarbonate (PC)
Processing Techniques	Injection Molding
INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Stress, brk, Type I, 5 mm/min	140	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	2.7	%	ASTM D638
Tensile Modulus, 5 mm/min	10810	MPa	ASTM D638
Flexural Stress	211	MPa	ASTM D790
Flexural Modulus	9040	MPa	ASTM D790
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, unnotched, 23°C	588	J/m	ASTM D4812
Izod Impact, notched, 23°C	77	J/m	ASTM D256
<b>THERMAL <sup>(1)</sup></b>			
HDT, 1.82 MPa, 3.2mm, unannealed	138	°C	ASTM D648
<b>PHYSICAL <sup>(1)</sup></b>			
Specific Gravity	1.26	-	ASTM D792
Mold Shrinkage, flow, 3.2 mm <sup>(2)</sup>	0.1 – 0.3	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm <sup>(2)</sup>	0.1 – 0.3	%	SABIC method
Melt Volume Rate, MVR at 300°C/5.0 kg	31	cm <sup>3</sup> /10 min	ISO 1133
<b>ELECTRICAL <sup>(1)</sup></b>			
Surface Resistivity <sup>(3)</sup>	1.E+03 – 1.E+05	Ω	ASTM D257
<b>INJECTION MOLDING <sup>(4)</sup></b>			
Drying Temperature	90 – 110	°C	
Drying Time	3 – 5	Hrs	
Melt Temperature	280 – 320	°C	
Nozzle Temperature	280 – 320	°C	

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Front - Zone 3 Temperature	280 – 320	°C	
Middle - Zone 2 Temperature	280 – 320	°C	
Rear - Zone 1 Temperature	250 – 280	°C	
Mold Temperature	90 – 120	°C	
Back Pressure	1 – 5	MPa	
Screw Speed	30 – 100	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Measurement meets requirements as specified in ASTM D4496.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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